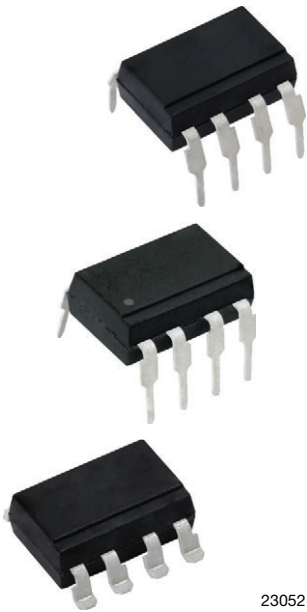
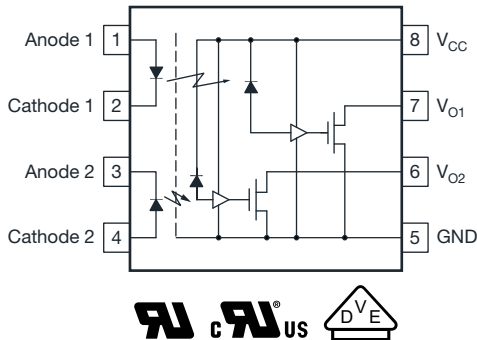


## High Speed Optocoupler, 10 MBd



23052



### DESCRIPTION

The VOH263A is a dual channel 10 MBd optocoupler utilizing high efficient input LEDs coupled to high speed integrated photo-detector logic gates. The detectors features an open drain outputs. The internal shield provides a guaranteed common mode transient immunity of 15 kV/μs.

### FEATURES

- Common mode rejection (CMR) of min. 15 kV/μs
- 3.3 V / 5 V dual supply voltage
- LVTTTL/LVCMOS compatibility
- Low power consumption
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT

### APPLICATIONS

- Microprocessor system interface
- Ground loop elimination
- Digital bus systems isolation
- High speed A/D and D/A conversion
- Digital control power supply
- Level shifting

### AGENCY APPROVALS

- UL1577 (pending)
- cUL (pending)
- DIN EN 60747-5-5 (VDE 0884-5), available with option 1 (pending)



ORDERING INFORMATION	
<div style="display: flex; justify-content: space-around; align-items: center;"> <div style="border: 1px solid black; padding: 2px 5px;">V</div> <div style="border: 1px solid black; padding: 2px 5px;">O</div> <div style="border: 1px solid black; padding: 2px 5px;">H</div> <div style="border: 1px solid black; padding: 2px 5px;">2</div> <div style="border: 1px solid black; padding: 2px 5px;">6</div> <div style="border: 1px solid black; padding: 2px 5px;">3</div> <div style="border: 1px solid black; padding: 2px 5px;">A</div> <div style="border: 1px solid black; padding: 2px 5px;">-</div> <div style="border: 1px solid black; padding: 2px 5px;">X</div> <div style="border: 1px solid black; padding: 2px 5px;">0</div> <div style="border: 1px solid black; padding: 2px 5px;">#</div> <div style="border: 1px solid black; padding: 2px 5px;">#</div> <div style="border: 1px solid black; padding: 2px 5px;">T</div> </div>	
PART NUMBER	PACKAGE OPTION
	TAPE AND REEL
<b>AGENCY CERTIFIED / PACKAGE</b>	
<b>UL, cUL</b>	
DIP-8	VOH263A
DIP-8, 400 mil (option 6)	VOH263A-X006
SMD-8 (option 7)	VOH263A-X007T
<b>UL, cUL, VDE (option 1)</b>	
DIP-8	VOH263A-X001
DIP-8, 400 mil (option 6)	VOH263A-X016
SMD-8 (option 7)	VOH263A-X017T

**Note**

- Additional options may be possible, please contact sales office

ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
<b>INPUT</b>				
Input forward current		$I_F$	20	mA
Reverse input voltage		$V_R$	5	V
Input power dissipation		$P_{diss}$	40	mW
<b>OUTPUT</b>				
Supply voltage		$V_{CC}$	7	V
Output current		$I_O$	50	mA
Output voltage		$V_O$	7	V
Output power dissipation		$P_{diss}$	85	mW
<b>COUPLER</b>				
Storage temperature		$T_{stg}$	-55 to +125	$^{\circ}\text{C}$
Operating temperature		$T_{amb}$	-40 to +110	$^{\circ}\text{C}$
Solder reflow temperature <sup>(1)</sup>	5 s		260	$^{\circ}\text{C}$

**Notes**

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability
- <sup>(1)</sup> Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP)

RECOMMENDED OPERATING CONDITIONS				
PARAMETER	SYMBOL	MIN.	MAX.	UNIT
Operating temperature	$T_{amb}$	-40	+110	$^{\circ}\text{C}$
Supply voltage	$V_{CC}$	2.7	3.6	V
	$V_{CC}$	4.5	5.5	V
Input current low level	$I_{FL}$	0	250	$\mu\text{A}$
Input current high level	$I_{FH}$	5	15	mA
Output pull up resistor	$R_L$	330	4000	$\Omega$
Fanout ( $R_L = 1\text{ k}\Omega$ )	N	-	5	TTL loads



TRUTH TABLE (positive logic)	
LED	OUTPUT
On	L
Off	H

ELECTRICAL CHARACTERISTICS ( $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+110\text{ }^{\circ}\text{C}$ , $2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}$ , $I_F = 7.5\text{ mA}$ , unless otherwise specified; typical values are at $V_{CC} = 3.3\text{ V}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$ )						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
<b>INPUT</b>						
Input forward voltage	$I_F = 10\text{ mA}$	$V_F$	-	1.38	1.8	V
Input forward voltage temperature coefficient	$I_F = 10\text{ mA}$	$\Delta V_F/\Delta T$	-	-1.5	-	mV/K
Input reverse voltage	$I_R = 10\text{ }\mu\text{A}$	$BV_R$	5	-	-	V
Input threshold current	$V_E = 2\text{ V}$ , $V_O = 0.6\text{ V}$ , $V_{CC} = 3.3\text{ V}$ , $I_{OL}(\text{sinking}) = 13\text{ mA}$	$I_{TH}$	-	2	5	mA
Input capacitance	$f = 1\text{ MHz}$ , $V_F = 0\text{ V}$	$C_I$	-	34	-	pF
<b>OUTPUT</b>						
Low level supply current	$I_F = 10\text{ mA}$ , $V_{CC} = 3.3\text{ V}$	$I_{CCL}$	-	6.4	10	mA
High level supply current	$I_F = 0\text{ mA}$ , $V_{CC} = 3.3\text{ V}$	$I_{CCH}$	-	6.8	10	mA
Low level output voltage	$V_{CC} = 3.3\text{ V}$ , $I_F = 5\text{ mA}$ , $I_{OL}(\text{sinking}) = 13\text{ mA}$	$V_{OL}$	-	0.24	0.6	V
High level output current	$V_{CC} = 3.3\text{ V}$ , $V_E = 2\text{ V}$ , $V_O = 3.3\text{ V}$ , $I_F = 250\text{ }\mu\text{A}$	$I_{OH}$	-	1.3	10	$\mu\text{A}$
<b>COUPLER</b>						
Input to output capacitance	$f = 1\text{ MHz}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$	$C_{IO}$	-	1	-	pF

**Note**

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements

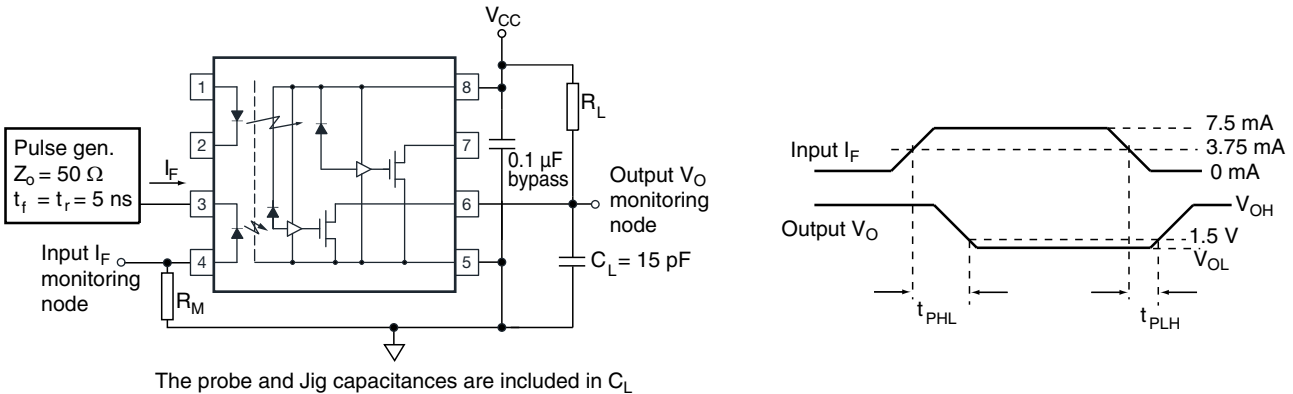
ELECTRICAL CHARACTERISTICS ( $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+110\text{ }^{\circ}\text{C}$ , $4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ , $I_F = 7.5\text{ mA}$ , unless otherwise specified; typical values are at $V_{CC} = 5.0\text{ V}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$ )						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
<b>INPUT</b>						
Input forward voltage	$I_F = 10\text{ mA}$	$V_F$	-	1.38	1.8	V
Input forward voltage temperature coefficient	$I_F = 10\text{ mA}$	$\Delta V_F/\Delta T$	-	-1.5	-	mV/K
Input reverse voltage	$I_R = 10\text{ }\mu\text{A}$	$BV_R$	5	-	-	V
Input threshold current	$V_E = 2\text{ V}$ , $V_O = 0.6\text{ V}$ , $V_{CC} = 5.5\text{ V}$ , $I_{OL}(\text{sinking}) = 13\text{ mA}$	$I_{TH}$	-	2.1	5	mA
Input capacitance	$f = 1\text{ MHz}$ , $V_F = 0\text{ V}$	$C_I$	-	34	-	pF
<b>OUTPUT</b>						
Low level supply current	$I_F = 10\text{ mA}$ , $V_{CC} = 5.5\text{ V}$	$I_{CCL}$	-	7.2	10	mA
High level supply current	$I_F = 0\text{ mA}$ , $V_{CC} = 5.5\text{ V}$	$I_{CCH}$	-	7.6	10	mA
Low level output voltage	$V_{CC} = 5.5\text{ V}$ , $I_F = 5\text{ mA}$ , $I_{OL}(\text{sinking}) = 13\text{ mA}$	$V_{OL}$	-	0.09	0.60	V
High level output current	$V_{CC} = 5.5\text{ V}$ , $V_O = 5.5\text{ V}$ , $I_F = 250\text{ }\mu\text{A}$	$I_{OH}$	-	1.12	10	$\mu\text{A}$
<b>COUPLER</b>						
Collector emitter capacitance	$f = 1\text{ MHz}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$	$C_{IO}$	-	4	-	pF

**Note**

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements

<b>SWITCHING CHARACTERISTICS</b> ( $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+110\text{ }^{\circ}\text{C}$ , $2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}$ , $I_F = 7.5\text{ mA}$ , unless otherwise specified; typical values are at $V_{CC} = 3.3\text{ V}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$ )						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to high output level	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_{PLH}$	20	50	90	ns
Propagation delay time to low output level	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_{PHL}$	25	44	75	ns
Pulse width distortion	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$ t_{PLH} - t_{PHL} $	-	10	-	ns
Propagation delay skew	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_{PSK}$	-	-	40	ns
Output rise time (10 % to 90 %)	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_r$	-	2.3	-	ns
Output fall time (90 % to 10 %)	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_f$	-	11	-	ns

<b>SWITCHING CHARACTERISTICS</b> ( $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+110\text{ }^{\circ}\text{C}$ , $4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ , $I_F = 7.5\text{ mA}$ , unless otherwise specified; typical values are at $V_{CC} = 5.0\text{ V}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$ )						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to high output level	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_{PLH}$	25	50	90	ns
	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$	$t_{PLH}$	-	-	100	ns
Propagation delay time to low output level	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_{PHL}$	25	40	90	ns
	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$ , $T_{amb} = 25\text{ }^{\circ}\text{C}$	$t_{PHL}$	-	-	100	ns
Pulse width distortion	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$ t_{PLH} - t_{PHL} $	-	10	-	ns
Propagation delay skew	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_{PSK}$	-	-	40	ns
Output rise time (10 % to 90 %)	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_r$	-	11	-	ns
Output fall time (90 % to 10 %)	$R_L = 350\ \Omega$ , $C_L = 15\text{ pF}$	$t_f$	-	2.3	-	ns


 Fig. 1 - Test Circuit for  $t_{PLH}$ ,  $t_{PHL}$ ,  $t_r$ , and  $t_f$

<b>COMMON MODE TRANSIENT IMMUNITY</b> ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Logic high common mode transient immunity	$V_{CC} = 3.3\text{ V}$ , $ V_{CM}  = 1000\text{ V}$ , $I_F = 0\text{ mA}$ , $V_O > 2.0\text{ V}$ , $R_L = 350\text{ }\Omega$	$ CM_H $	15 000	-	-	$\text{V}/\mu\text{s}$
	$V_{CC} = 5\text{ V}$ , $ V_{CM}  = 1000\text{ V}$ , $I_F = 0\text{ mA}$ , $V_O > 2.0\text{ V}$ , $R_L = 350\text{ }\Omega$	$ CM_H $	15 000	-	-	$\text{V}/\mu\text{s}$
Logic low common mode transient immunity	$V_{CC} = 5\text{ V}$ , $ V_{CM}  = 1000\text{ V}$ , $I_F = 10\text{ mA}$ , $V_O < 0.8\text{ V}$ , $R_L = 350\text{ }\Omega$	$ CM_L $	15 000	-	-	$\text{V}/\mu\text{s}$
	$V_{CC} = 5\text{ V}$ , $ V_{CM}  = 1000\text{ V}$ , $I_F = 10\text{ mA}$ , $V_O < 0.8\text{ V}$ , $R_L = 350\text{ }\Omega$	$ CM_L $	15 000	-	-	$\text{V}/\mu\text{s}$

**Notes**

- No external pull up is required for a high logic state on the enable input. If the enable pin is not used, connect it to  $V_{CC}$

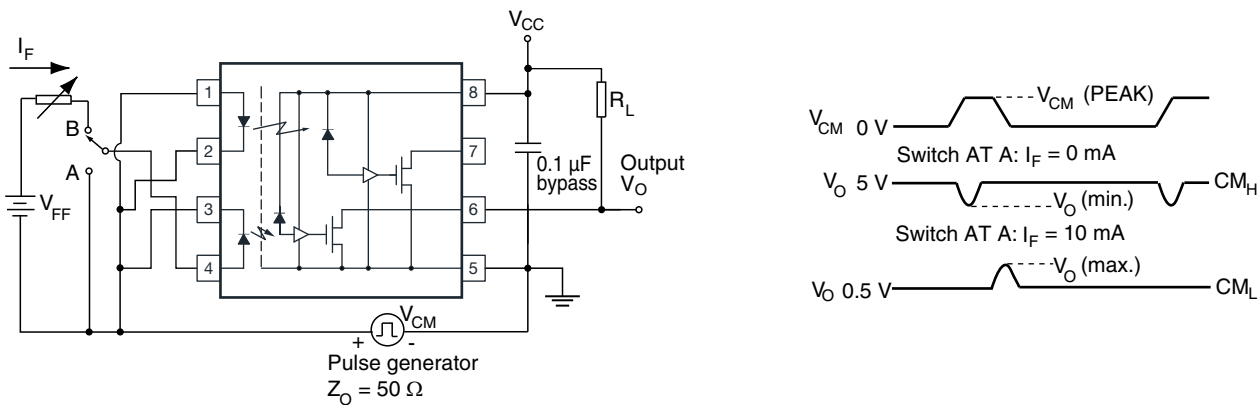


Fig. 2 - Test Circuit for Common Mode Transient Immunity

<b>SAFETY AND INSULATION RATINGS</b>				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		55 / 110 / 21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, $t = 1\text{ min}$	$V_{ISO}$	5000	$V_{RMS}$
Maximum transient isolation voltage	According to DIN EN 60747-5-5	$V_{IOTM}$	6000	$V_{peak}$
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	$V_{IORM}$	630	$V_{peak}$
Isolation resistance	$T_{amb} = 25\text{ }^{\circ}\text{C}$ , $V_{IO} = 500\text{ V}$	$R_{IO}$	$\geq 10^{12}$	$\Omega$
Maximum output power dissipation		$P_{SO}$	600	mW
Maximum input current		$I_{SI}$	230	mA
Maximum ambient temperature (derated)		$T_S$	175	$^{\circ}\text{C}$
Creepage distance	DIP-8, SMD-8		$\geq 7$	mm
	DIP-8, 400 mil		$\geq 8$	mm
Clearance distance	DIP-8, SMD-8		$\geq 7$	mm
	DIP-8, 400 mil		$\geq 8$	mm
Insulation thickness		DTI	$\geq 0.4$	mm

**TYPICAL CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

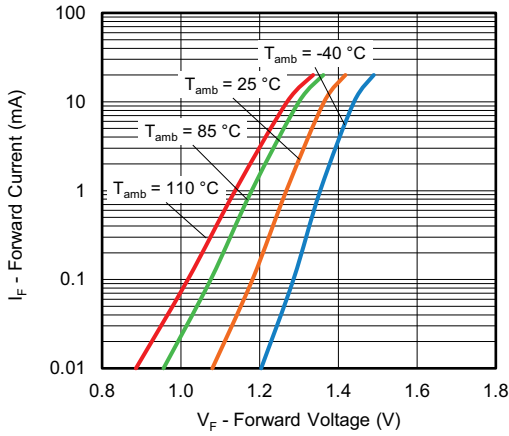


Fig. 3 - Diode Forward Current vs. Forward Voltage

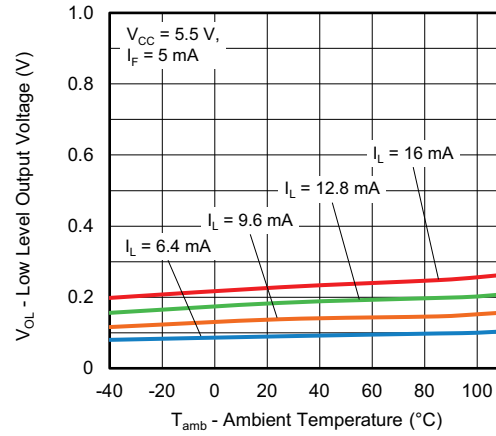


Fig. 6 - Low Level Output Voltage vs. Ambient Temperature

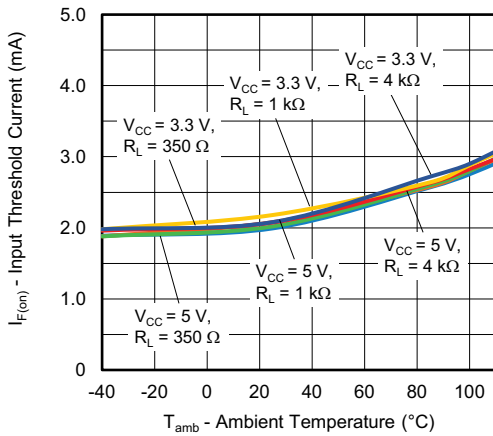


Fig. 4 - Input Threshold Current vs. Ambient Temperature

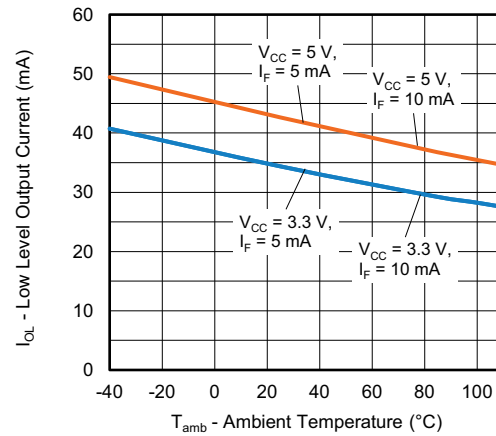


Fig. 7 - Low Level Output Current vs. Ambient Temperature

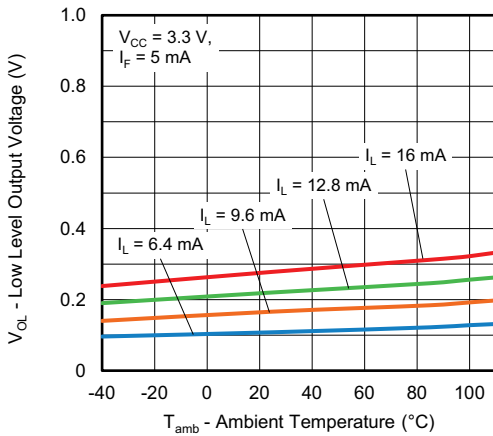


Fig. 5 - Low Level Output Voltage vs. Ambient Temperature

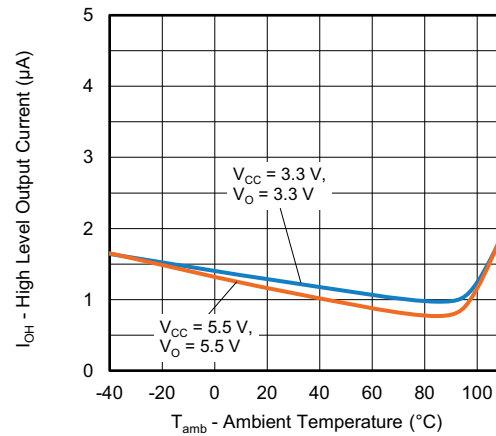


Fig. 8 - High Level Output Current vs. Ambient Temperature

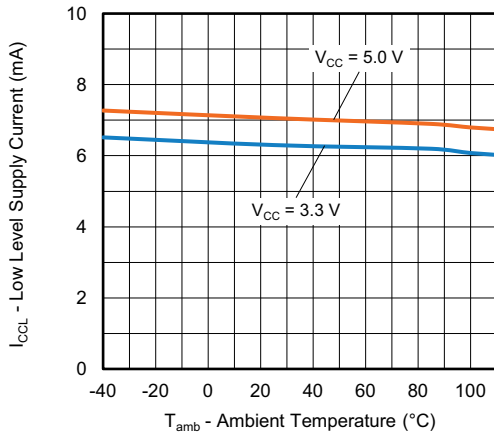


Fig. 9 - Low Level Supply Current vs. Ambient Temperature

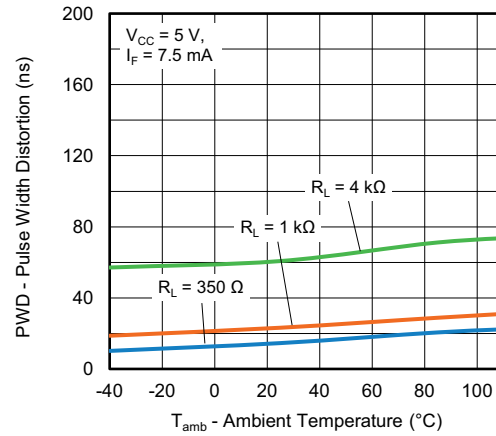


Fig. 12 - Pulse Width Distortion vs. Ambient Temperature

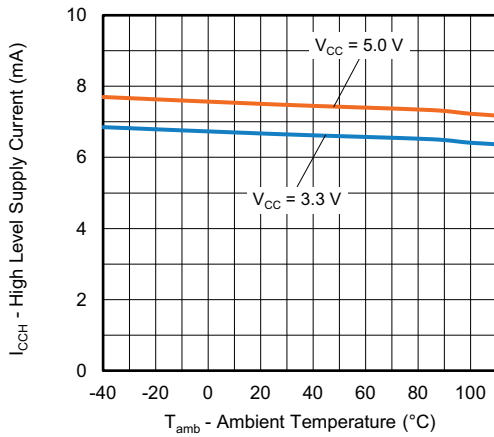


Fig. 10 - High Level Supply Current vs. Ambient Temperature

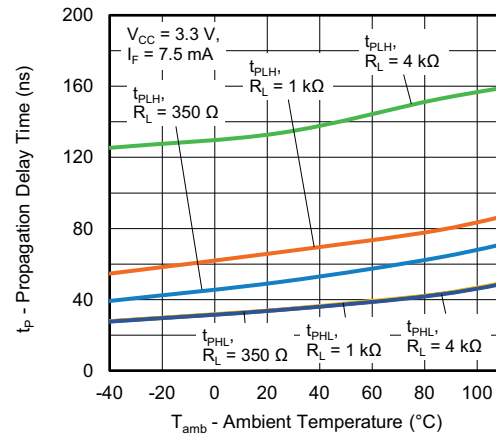


Fig. 13 - Propagation Delay Time vs. Ambient Temperature

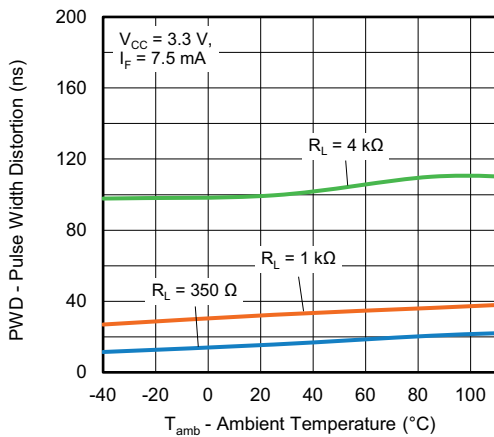


Fig. 11 - Pulse Width Distortion vs. Ambient Temperature

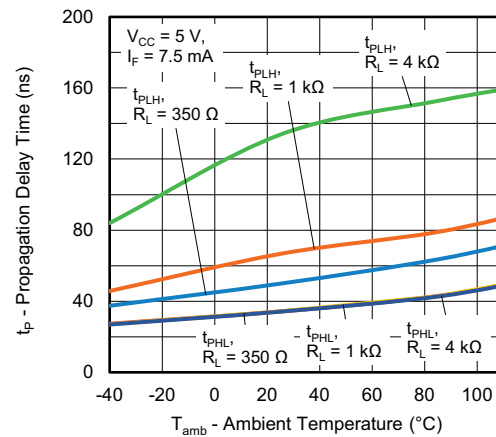


Fig. 14 - Propagation Delay Time vs. Ambient Temperature

**PACKAGE DIMENSIONS** (in millimeters)

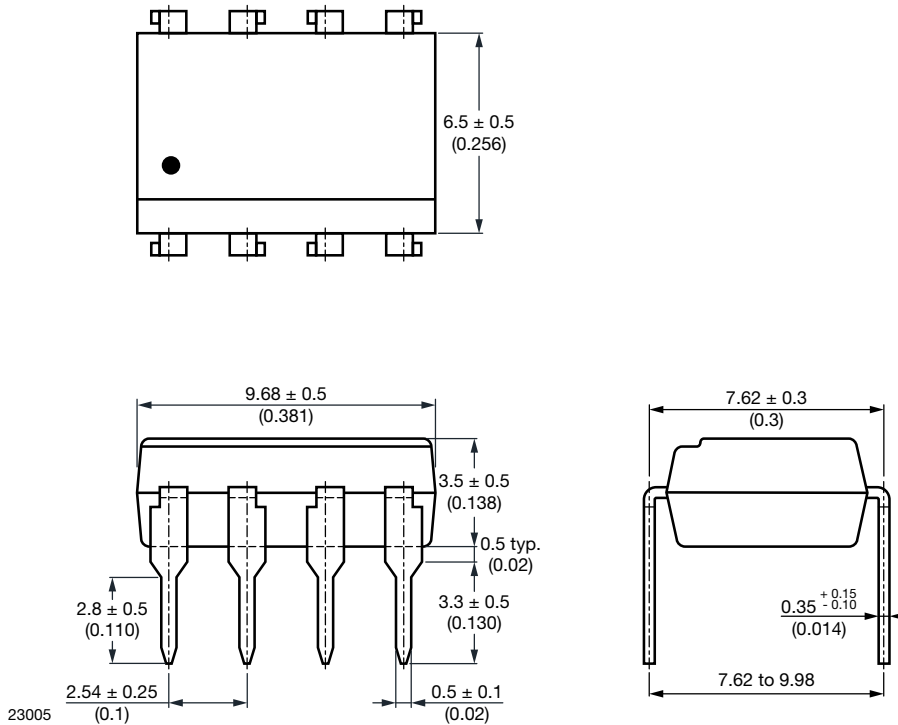
**DIP-8**


Fig. 15

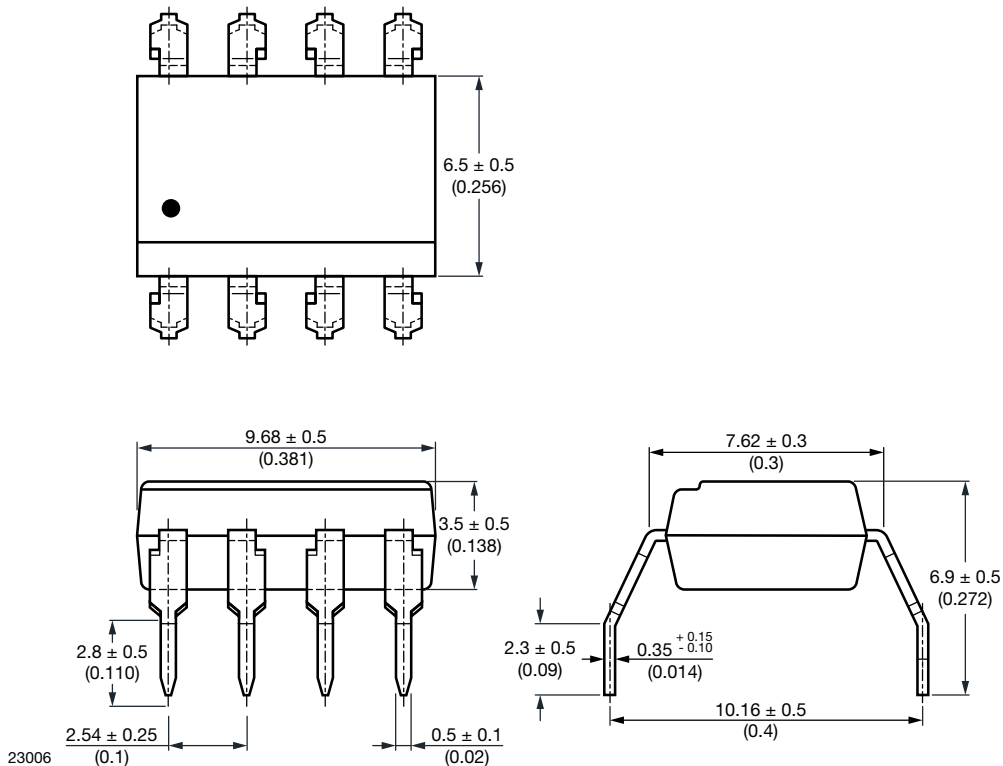
**DIP-8, 400 mil**


Fig. 16



SMD-8

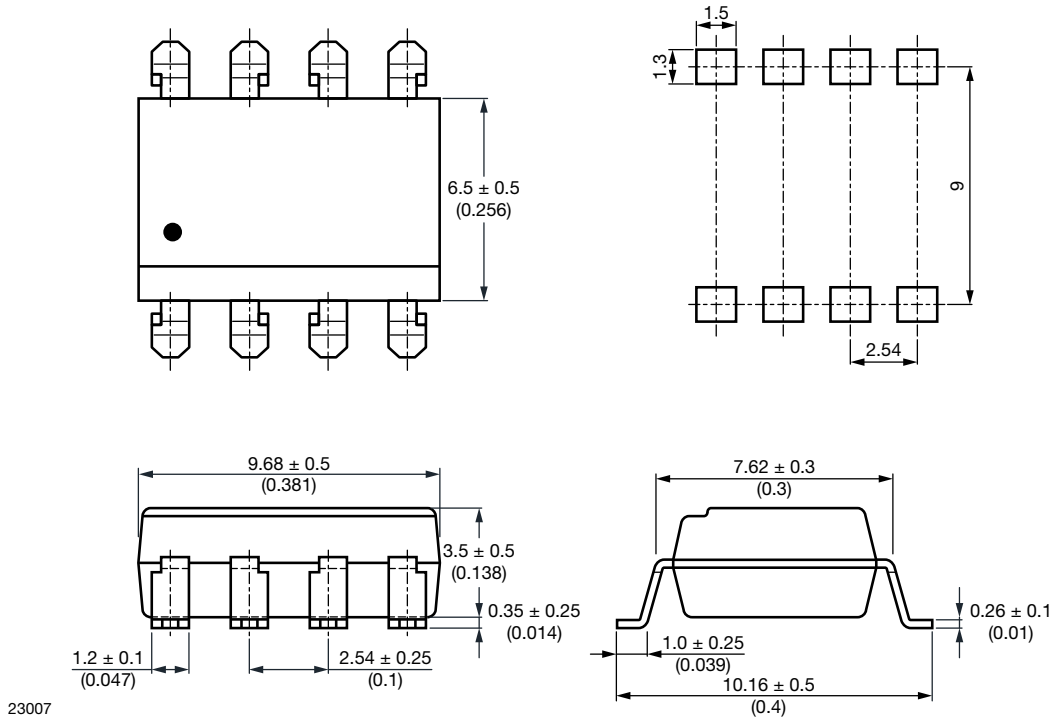


Fig. 17

PACKAGE MARKING

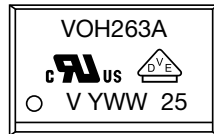


Fig. 18 - Example of VOH263A

Notes

- “YWW” is the date code marking (Y = year code, WW = week code)
- VDE logo is only marked on VDE option parts
- Tape and reel suffix (T) is not part of the package marking

**PACKAGING INFORMATION** (in millimeters)

DEVICES PER TUBES			
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX
DIP-8	50	16	800
DIP-8, 400 mil	50	16	800

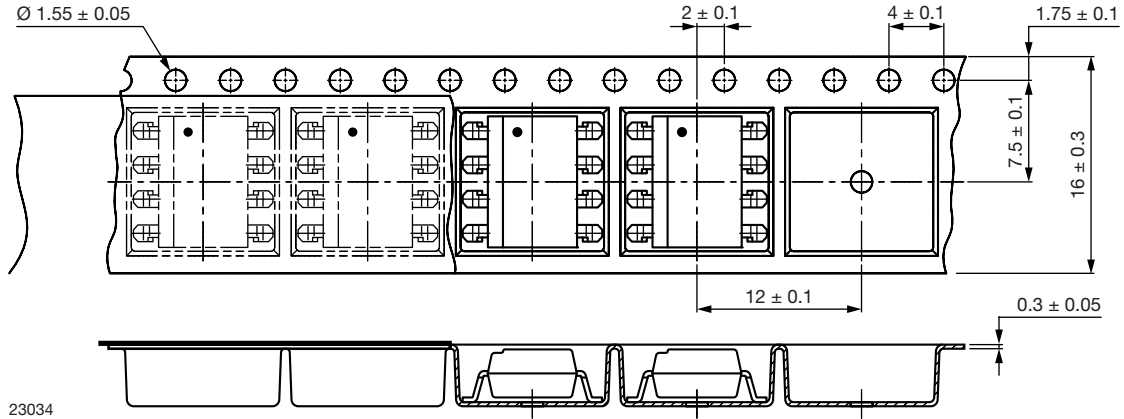
**SMD-8 Tape**


Fig. 19 - Tape and Reel Packaging (1000 pieces on reel)

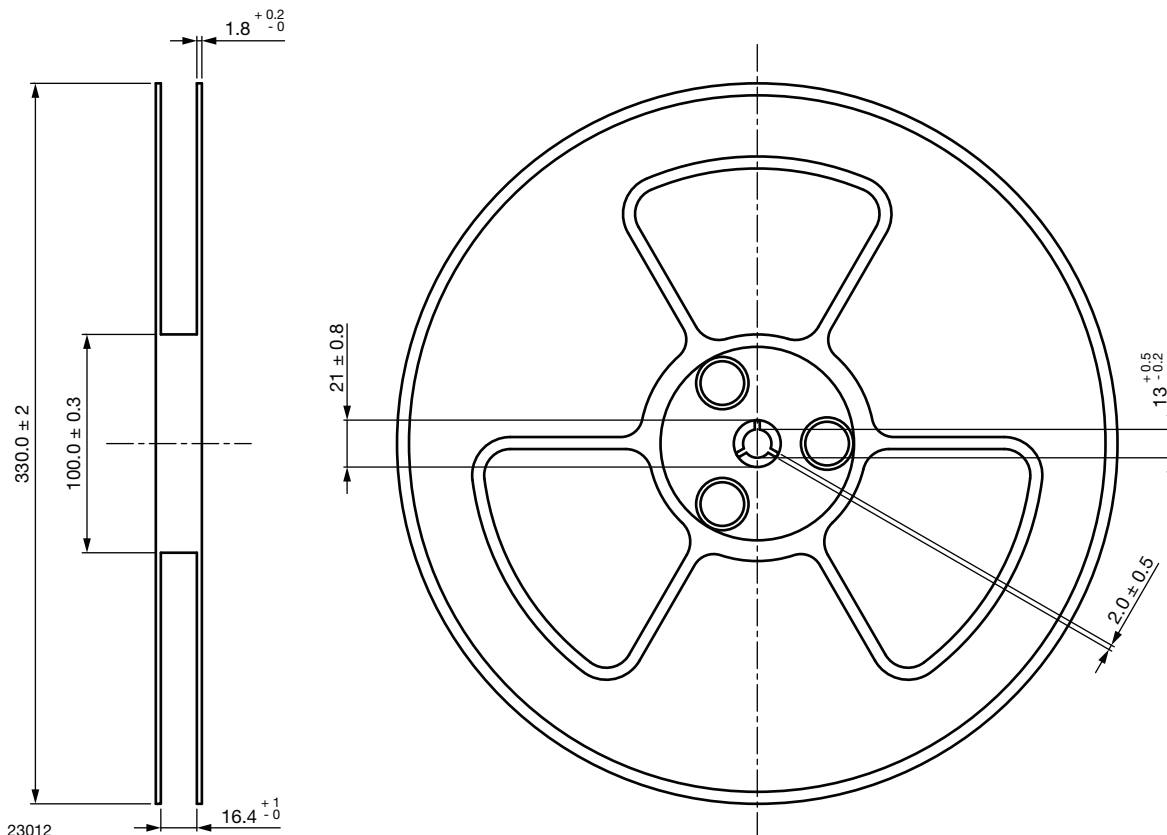
**Reel**


Fig. 20 - Tape and Reel Shipping Medium

**SOLDER PROFILES**
**IR Reflow Soldering (JEDEC® J-STD-020C compliant)**

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

PROFILE ITEM	CONDITIONS
Preheat	
- Temperature minimum ( $T_{S \min.}$ )	150 °C
- Temperature maximum ( $T_{S \max.}$ )	200 °C
- Time (min. to max.) ( $t_s$ )	90 s $\pm$ 30 s
Soldering zone	
- Temperature ( $T_L$ )	217 °C
- Time ( $t_L$ )	60 s
Peak temperature ( $T_p$ )	260 °C
Ramp-up rate	3 °C/s max.
Ramp-down rate	3 °C/s to 6 °C/s

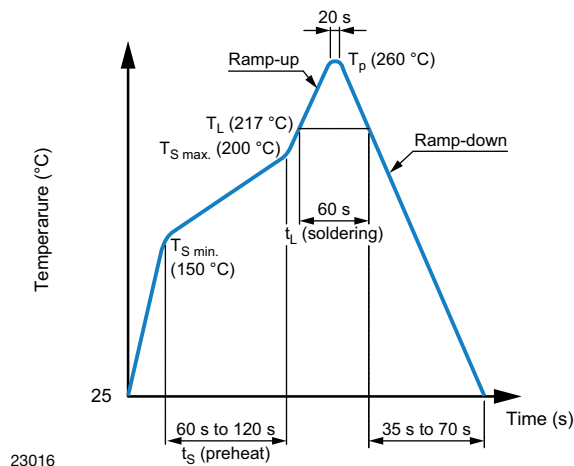


Fig. 1

**Wave Soldering (JEDEC JESD22-A111 compliant)**

One time soldering is recommended within the condition of temperature.

Temperature: 260 °C + 0 °C / - 5 °C

Time: 10 s

Preheat temperature: 25 °C to 140 °C

Preheat time: 30 s to 80 s

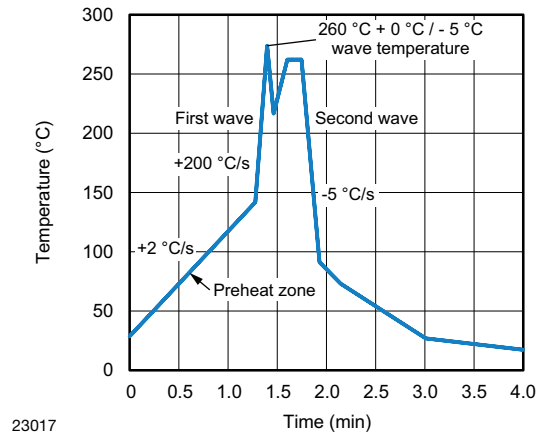


Fig. 2

**Hand Soldering by Soldering Iron**

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380 °C + 0 °C / - 5 °C

Time: 3 s max.

**HANDLING AND STORAGE CONDITIONS**

ESD level: HBM class 2

Floor life: unlimited

Conditions:  $T_{amb} < 30$  °C, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

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